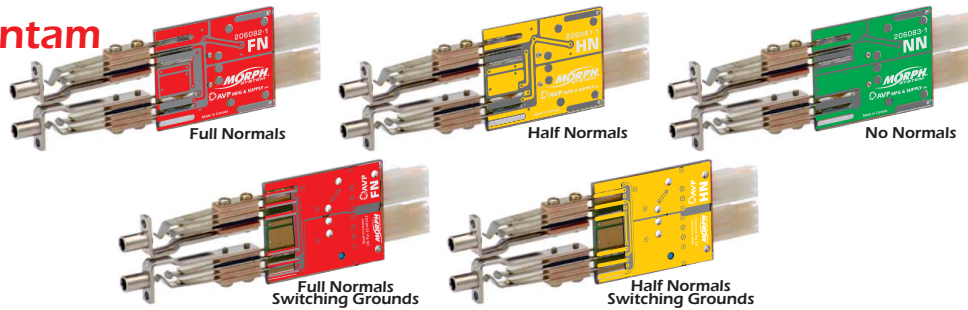
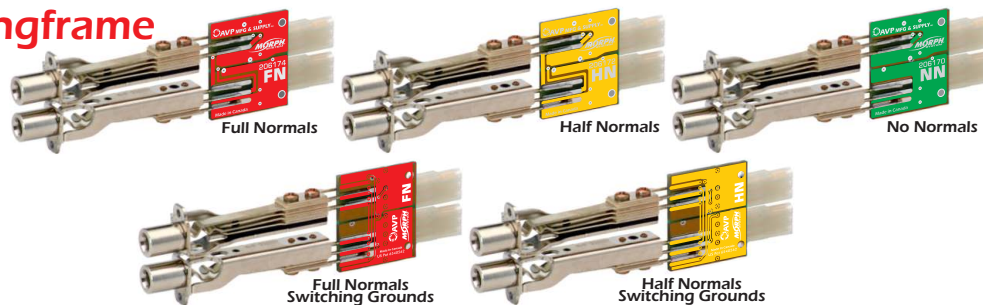


- **Advanced Audio Patchbay Concept**
- **Next Generation Flexibility**
- **AES/EBU Digital and Analog Audio Application**

Bantam



Longframe

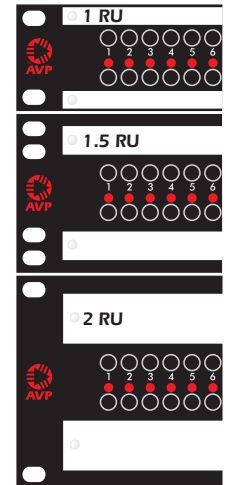
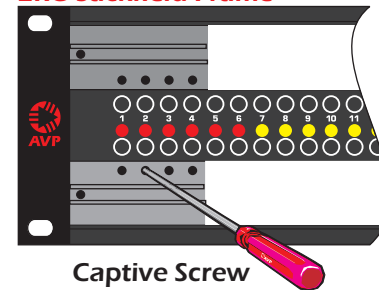


Application: AES/EBU, Analog

- Morph modules can be effortlessly identified, mixed and changed. Entire racks of jackfields can be re-configured anytime
- EDAC/ELCO 3 pin interface
- Modules are front mounted, providing a simple module interchange method
- Maximized designations

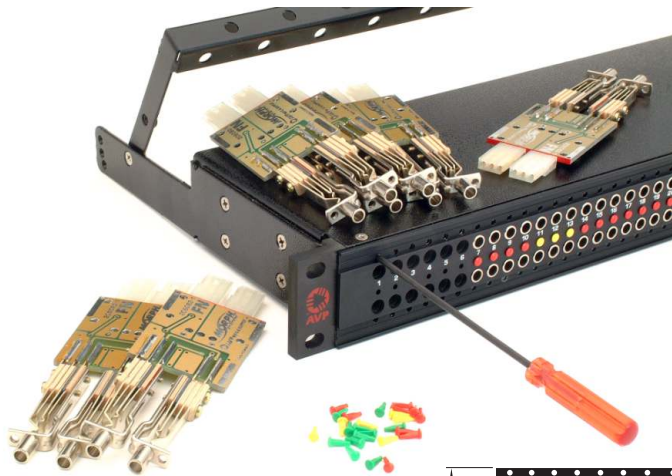


2RU Jackfield Frame

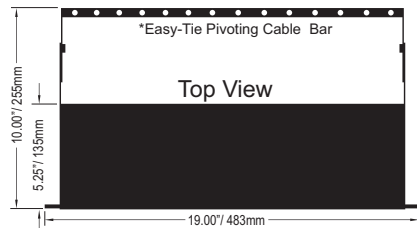


The award-winning Morph Audio System excels in specialty application requirements as found in mobile units and harsh environments. Its EDAC 3-pin term-

inations can withstand a 50 gravity vibration with no loss of continuity. In addition, the Morph System's short depth and light weight, allows installation in the tightest spaces.



Keep an inventory of Morph Modules and empty Morph frames to allow custom patchbay assembly or re-configuration in minutes! Morph modules fit 1, 1.5 & 2 Rack Unit frames.



CRIMP CHARACTERISTICS

- Contacts and Crimp Tools Accommodate from 28 AWG to 18 AWG, Solid or Stranded Conductor Diameters from .012" (0.30) to .049" (1.25) and an Insulation Diameter up to .074" (1.88)
- Multiple Smaller Gauge Wires may be Crimped Together
- Crimp Resistance from 0.5 Milliohms (18 AWG) to 1.5 Milliohms (28AWG)

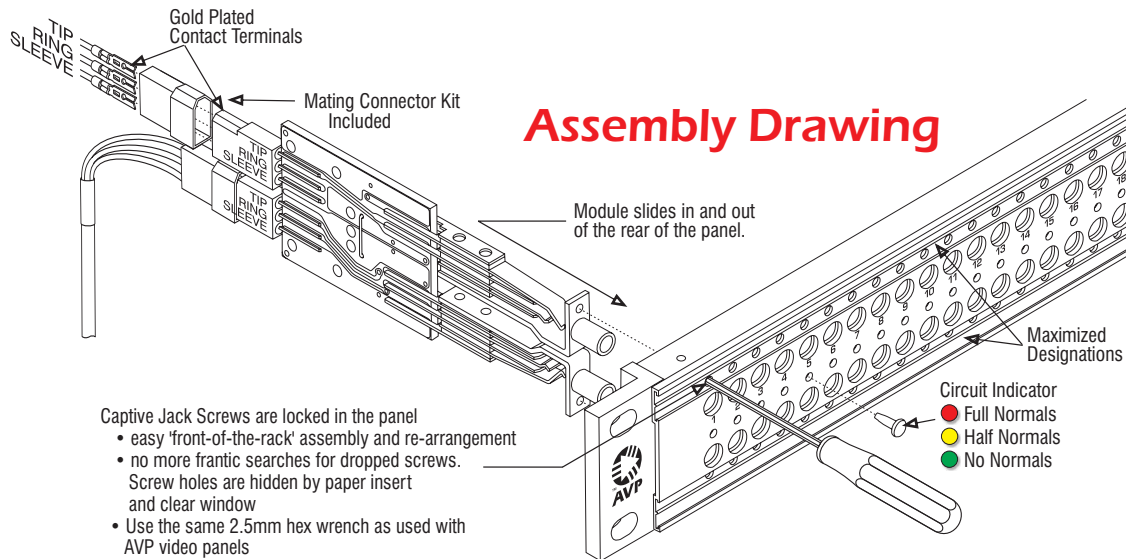


Mating Connector Kit

Each Morph Patchbay is shipped complete with its crimp-pin mating connector kit and a captive hex driver. (See ordering information for more details)

Mating Connector Kits, below, do not include the captive hex driver. Please contact AVP if required.

- MK224P-E03C** EDAC 3Pin Primaries Kit for 2x24 Patchbay, Crimp
- MK226P-E03C** EDAC 3Pin Primaries Kit for 2x26 Patchbay, Crimp
- MK224P-E03S** EDAC 3Pin Primaries Kit for 2x24 Patchbay, Solder
- MK226P-E03S** EDAC 3Pin Primaries Kit for 2x26 Patchbay, Solder



Assembly Drawing

Tooling



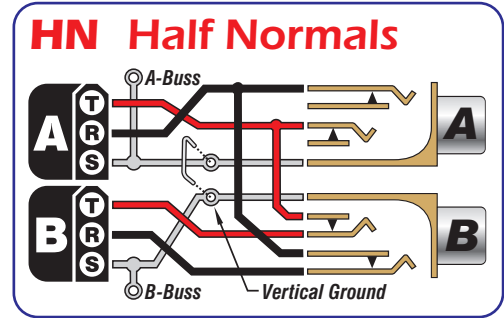
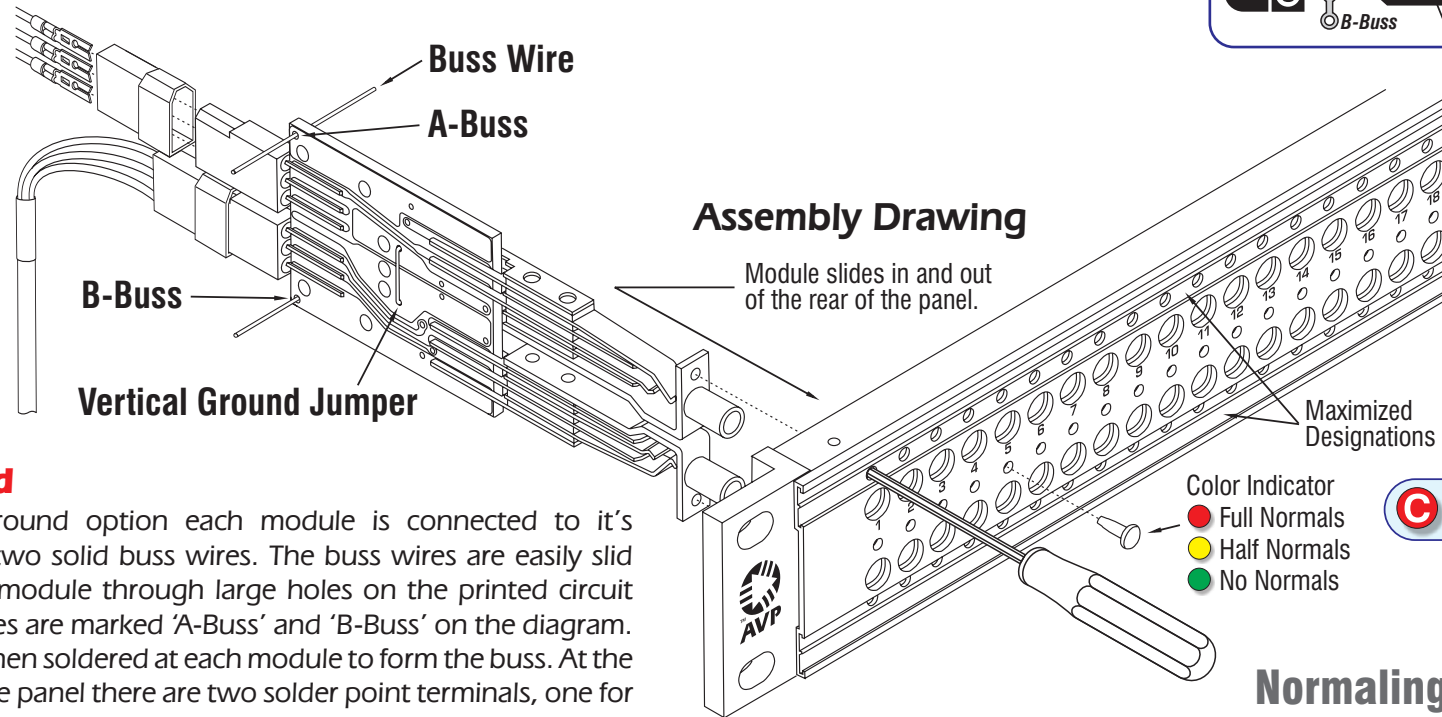


Morph Module Grounding

All modules in the Morph line offer a number of options for the shield connections of the jacks. Most common are the 'Vertical Ground' and 'Bussed Ground'.

Vertical Ground

The Vertical Ground option connects the shield from the 'A' row jack (top row) to the 'B' row jack (bottom row). This is accomplished by inserting a solid wire jumper that is the same shape and size as a standard paper staple into a set of holes on the module's printed circuit board. The jumper is then soldered in place to complete the connection.



Buss Ground

For the Buss Ground option each module is connected to its neighbour with two solid buss wires. The buss wires are easily slid from module to module through large holes on the printed circuit board. These holes are marked 'A-Buss' and 'B-Buss' on the diagram. The buss wire is then soldered at each module to form the buss. At the left rear side of the panel there are two solder point terminals, one for the A row and one for the B row. The buss wire is connected to the terminal on the inside of the jackfield and provides the customer a location for making external connection to the busses.

To remove a module after applying the Buss Ground option, it is necessary to cut the buss wire on either side of the module to be removed. After the module is replaced a short buss wire can be re-attached to the cut end of the main buss wire to re-establish the buss grounds across the jackfield.



Normaling Descriptions

T: Tip	TN: Tip Normal
R: Ring	RN: Ring Normal
S: Sleeve	SN: Sleeve Normal

*US Patent No. 6,540,562